

Applicant: Dong-Ho Lee  
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For: STACK PACKAGE MADE OF CHIP SCALE PACKAGES

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**FOREIGN PATENT DOCUMENTS**

| <u>Exam</u> | <u>Init</u> | <u>Ref</u> | <u>Document Number</u> | <u>Publication Date</u> | <u>Country</u> | <u>Name</u>  |
|-------------|-------------|------------|------------------------|-------------------------|----------------|--------------|
|             | <u>TL</u>   | —          | JP2000-216327          | 4/8/2000                | Japan          | Oda Toshiaki |
|             | <u>IL</u>   | —          | KR2001-11310           | 2/15/2001               | Korea          | Jang and Ko  |
|             | <u>PL</u>   | —          | KR2001-28845           | 4/6/2001                | Korea          | Kim and Lee  |

**OTHER DOCUMENTS**

| <u>Exam</u> | <u>Init</u> | <u>Ref</u> | <u>Author, Title, Date, Pertinent Pages, Etc.)</u>  |
|-------------|-------------|------------|---|
|             | <u>PL</u>   | —          | English language of Abstract for Japanese Patent Publication No. JP2000-216327, published 4/8/2000. |
|             | <u>IL</u>   | —          | English language of Abstract for Korean Patent Publication No. KR2001-11310, published 2/15/2001.   |
|             | <u>PL</u>   | —          | English language of Abstract for Korean Patent Publication No. KR2001-28845, published 4/6/2001.    |

Examiner: 

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